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2.5V / 3.3V Any Differential Clock IN to Differential LVPECL OUT ÷1/2/4/8, ÷2/4/8/16 Clock Divider

Description

The NB6L239 is a high–speed, low skew clock divider with two divider circuits, each having selectable clock divide ratios; $\div 1/2/4/8$ and $\div 2/4/8/16$. Both divider circuits drive a pair of differential LVPECL outputs. (More device information on page 7). The NB6L239 is a member of the ECLinPS MAXTM Family of the high performance clock products.

Features

- Maximum Clock Input Frequency, 3.0 GHz
- CLOCK Inputs Compatible with LVDS/LVPECL/CML/HSTL/HCSL
- EN, MR, and SEL Inputs Compatible with LVTTL/LVCMOS
- Rise/Fall Time 65 ps Typical
- < 10 ps Typical Output-to-Output Skew
- Example: 622.08 MHz Input Generates 38.88 MHz to 622.08 MHz Outputs
- Internal 50 Ω Termination Provided
- Random Clock Jitter < 1 ps RMS
- QA ÷ 1 Edge Aligned to QB ÷ n Edge
- Operating Range: $V_{CC} = 2.375 \text{ V}$ to 3.465 V with $V_{EE} = 0 \text{ V}$
- Master Reset for Synchronization of Multiple Chips
- V_{BBAC} Reference Output
- Synchronous Output Enable/Disable
- These Devices are Pb-Free and are RoHS Compliant



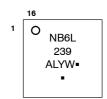
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MARKING DIAGRAM*



QFN-16 MN SUFFIX CASE 485G



A = Assembly Location

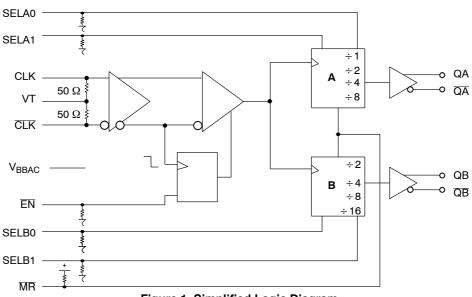
L = Wafer Lot Y = Year W = Work Week • Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 11 of this data sheet.



1

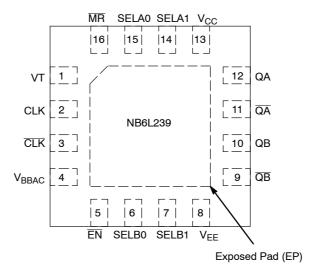


Figure 2. Pinout: QFN-16 (Top View)

Table 1. PIN DESCRIPTION

Pin	Name	I/O	Description		
1	VT		Internal 100 Ω Center-Tapped Termination Pin for CLK and $\overline{\text{CLK}}$.		
2	CLK	LVPECL, CML, LVDS, HCSL, HSTL Input	Noninverted Differential CLOCK Input.		
3	CLK	LVPECL, CML, LVDS, HCSL, HSTL Input	Inverted Differential CLOCK Input.		
4	V _{BBAC}		Output Voltage Reference for Capacitor Coupled Inputs, Only.		
5	EN*	LVCMOS/LVTTL Input	Synchronous Output Enable		
6	SELB0*	LVCMOS/LVTTL Input	Clock Divide Select Pin		
7	SELB1*	LVCMOS/LVTTL Input	Clock Divide Select Pin		
8	V _{EE}	Power Supply	Negative Supply Voltage		
9	QB	LVPECL Output	Inverted Differential Output. Typically terminated with 50 Ω resistor to V _{CC} – 2.0 V.		
10	QB	LVPECL Output	Noninverted Differential Output. Typically terminated with 50 Ω resistor to V _{CC} – 2.0 V.		
11	QA	LVPECL Output	Inverted Differential Output. Typically terminated with 50 Ω resistor to V _{CC} – 2.0 V.		
12	QA	LVPECL Output	Noninverted Differential Output. Typically terminated with 50 Ω resistor to V _{CC} – 2.0 V.		
13	V _{CC}	Power Supply	Positive Supply Voltage.		
14	SELA1*	LVCMOS/LVTTL Input	Clock Divide Select Pin		
15	SELA0*	LVCMOS/LVTTL Input	Clock Divide Select Pin		
16	MR**	LVCMOS/LVTTL Input	Master Reset Asynchronous, Default Open High, Asserted LOW		
	EP	Power Supply (OPT)	The Exposed Pad on the QFN–16 package bottom is thermally connected to the die for improved heat transfer out of package. The pad is electrically connected to the die, and is recommended to be electrically and thermally connected to V_{EE} on the PC board.		

^{*}Pins will default LOW when left OPEN.
**Pins will default HIGH when left OPEN.

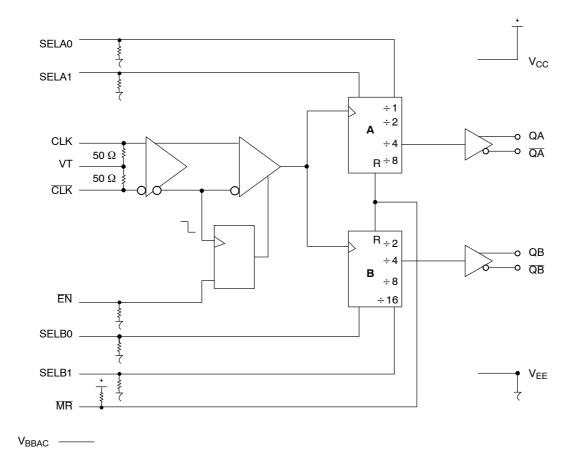


Figure 3. Logic Diagram

Table 2. FUNCTION TABLE

CLK	EN*	MR**	FUNCTION
Z Z	L H X	IΙL	Divide Hold Q Reset Q

Table 3. CLOCK DIVIDE SELECT, QA OUTPUTS

SELA1*	SELA0*	QA Outputs
L H H	L H L H	Divide by 1 Divide by 2 Divide by 4 Divide by 8

Table 4. CLOCK DIVIDE SELECT, QB OUTPUTS

SELB1*	SELB0*	QB Outputs
L L H	L H L H	Divide by 2 Divide by 4 Divide by 8 Divide by 16

X = Don't Care

^{*}Pins will default LOW when left OPEN. **Pins will default HIGH when left OPEN.

Table 5. ATTRIBUTES

Characteristics		Value
Internal Input Pulldown Resistor Internal Input Pullup Resistor		75 kΩ 75 kΩ
ESD Protection	> 1500 V > 150 V > 1000 V	
Moisture Sensitivity, Indefinite Time Out of D	Orypack (Note 1)	Pb-Free Pkg
	QFN-16	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count		367
Meets or exceeds JEDEC Spec EIA/JESD7	8 IC Latchup Test	

^{1.} For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Mode Power Supply	V _{EE} = 0 V		3.6	V
VI	Input Voltage	V _{EE} = 0 V	$V_{EE} \le V_I \le V_{CC}$	3.6	V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
I _{BB}	V _{BBAC} Sink/Source Current			± 0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm		41.6 35.2	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board		4.0	°C/W
T _{sol}	Wave Solder Pb-Free			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 6. DC CHARACTERISTICS, CLOCK INPUTS, LVPECL OUTPUTS

 $(V_{CC} = 2.375 \text{ V to } 3.465 \text{ V}, V_{EE} = 0 \text{ V})$

			-40°C			25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	
I _{EE}	Power Supply Cur- rent	30	40	50	30	40	50	30	40	50	mA	
V _{OH}	Output HIGH Voltage (Notes 2, 3) V _{CC} = 3.3 V V _{CC} = 2.5 V	V _{CC} -1150 2150 1350	V _{CC} -1060 2240 1440	V _{CC} -950 2350 1550	V _{CC} -1100 2200 1400	V _{CC} -1015 2285 1485	V _{CC} - 900 2400 1600	V _{CC} -1050 2250 1450	V _{CC} -980 2320 1520	V _{CC} - 850 2450 1650	mV	
V _{OL}	Output LOW Voltage (Notes 2, 3) V _{CC} = 3.3 V V _{CC} = 2.5 V	V _{CC} -1935 1365 565	V _{CC} -1775 1525 725	V _{CC} -1630 1670 870	V _{CC} -1875 1430 630	V _{CC} -1735 1565 765	V _{CC} -1580 1720 920	V _{CC} -1810 1490 690	V _{CC} -1675 1625 825	V _{CC} -1530 1770 970	mV	

DIFFERENTIAL INPUT DRIVEN SINGLE-ENDED (Figures 7, 10)

V _{th}	Input Threshold Reference Voltage (Note 4)	100		V _{CC} – 100	100		V _{CC} – 100	100		V _{CC} – 100	mV
V _{IH}	Single-ended Input HIGH Voltage	V _{th} + 100		V _{CC}	V _{th} + 100		V _{CC}	V _{th} + 100		V _{CC}	mV
V _{IL}	Single-ended Input LOW Voltage	V _{EE}		V _{th} – 100	V _{EE}		V _{th} – 100	V _{EE}		V _{th} – 100	mV
V _{BBAC}	Output Voltage Reference @ 100 μ A (Note 7) $V_{CC} = 3.3 \text{ V}$ $V_{CC} = 2.5 \text{ V}$	V _{CC} -1460 1840 1040	V _{CC} -1330 1970 1170	V _{CC} -1200 2100 1300	V _{CC} -1460 1840 1040	V _{CC} -1340 1960 1160	V _{CC} -1200 2100 1300	V _{CC} -1460 1840 1040	V _{CC} -1350 1950 1150	V _{CC} -1200 2100 1300	mV

DIFFERENTIAL INPUT DRIVEN DIFFERENTIALLY (Figures 8, 9, 11) (Note 6)

V _{IHD}	Differential Input HIGH Voltage	100		V _{CC}	100		V _{CC}	100		V _{CC}	mV
V _{ILD}	Differential Input LOW Voltage	V _{EE}		V _{CC} – 100	V _{EE}		V _{CC} – 100	V _{EE}		V _{CC} – 100	mV
V _{CMR}	Input Common Mode Range (Differ- ential Cross-point Voltage) (Note 5)	50		V _{CC} – 50	50		V _{CC} – 50	50		V _{CC} – 50	mV
V _{ID}	Differential Input Voltage (V _{IHD(CLK)} – V _{ILD(CLK)}) and (V _{IHD(CLK)} –V _{ILD(CLK)})	100		V _{CC} - V _{EE}	100		V _{CC} - V _{EE}	100		V _{CC} - V _{EE}	mV
R _{TIN}	Internal Input Ter- mination Resistor	45	50	55	45	50	55	45	50	55	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 2. Input and output parameters vary 1:1 with V_{CC} .
- 3. Outputs loaded with 50 Ω to V_{CC} 2.0 V for proper operation.

- Vth is applied to the complementary input when operating in single-ended mode.
 VCMR_{MIN} varies 1:1 with V_{EE}, VCMR_{MAX} varies 1:1 with V_{CC}.
 Input and output voltage swing is a single-ended measurement operating in differential mode.
- 7. V_{BBAC} used to rebias capacitor-coupled inputs only (see Figures 16 and 17).

Table 7. DC CHARACTERISTICS, LVTTL/LVCMOS INPUTS ($V_{CC} = 2.375 \text{ V}$ to 3.465 V, $V_{EE} = 0 \text{ V}$, $T_{A} = -40 ^{\circ}\text{C}$ to $+85 ^{\circ}\text{C}$)

Symbol	Characteristic	Min	Тур	Max	Unit
V _{IH}	Input HIGH Voltage (LVCMOS/LVTTL)	2.0		V _{CC}	V
V _{IL}	Input LOW Voltage (LVCMOS/LVTTL)	V _{EE}		0.8	V
I _{IH}	Input HIGH Current	-150		150	μΑ
I _{IL}	Input LOW Current	-150		150	μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

Table 8. AC CHARACTERISTICS V_{CC} = 2.375 V to 3.465 V; V_{EE} = 0 V (Note 8)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{inMAX}	Maximum Input CLOCK Frequency	3.0			3.0			3.0			GHz
V _{OUTPP}	$\begin{array}{lll} \text{Output Voltage Amplitude (Notes 10, 11)} \\ \text{QA}(\div2,4,8),\text{QB}(\divn) & f_{in} \leq 3.0 \;\text{GHz} \\ \text{QA}(\div1),\text{QB}(\divn) & f_{in} \leq 2.5 \;\text{GHz} \\ \text{QA}(\div1),\text{QB}(\divn) & 2.5 \;\text{GHz} < f_{in} \leq 3.0 \;\text{GHz} \end{array}$	450 450 300	650 650 650		450 450 250	650 630 650		450 450 200	650 610 650		mV
t _{PLH} , t _{PHL}	Propagation Delay to CLK, Qn Output Differential @ 50 MHz MR, Qn	370 330	470 370	570 430	370 330	470 380	570 430	400 330	500 400	600 480	ps
t _{RR}	Reset Recovery	0	-90		0	-90		0	-90		ps
t _s	Setup Time @ 50 MHz EN, CLK SELA/B, CLK	0 0	-60 -300		0	-60 -300		0 0	-60 -300		ps
t _h	Hold Time @ 50 MHz CLK, EN CLK, SELA/B	150 700	65 200		150 700	65 200		150 700	65 200		ps
t _{skew}	Within-Device Skew @ 50 MHz (Note 9) Device-to-Device Skew (Note 9) Duty Cycle Skew (Note 9)		5 25 25	30 80 40		5 30 30	30 90 45		6 30 30	35 90 45	ps
t _{PW}	Minimum Pulse Width MR	550			550			550			ps
t _{JITTER}	RMS Random Clock Jitter (See Figure 20. F _{max} /JITTER)			< 1			< 1			< 1	ps
V _{INPP}	Input Voltage Swing (Differential Configuration) (Note 10)	100		V _{CC} -V _{EE}	100		V _{CC} -V _{EE}	100		V _{CC} -V _{EE}	mV
t _r t _f	Output Rise/Fall Times @ 50 MHz Qn, Qn (20% – 80%)	30	60	120	30	65	120	30	70	120	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 8. Measured using a 750 mV, 50% duty cycle clock source. All loading with 50 Ω to V_{CC} 2.0 V.
- 9. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation
- when the delays are measured from the cross point of the inputs to the cross point of the outputs.

 10. Input and output voltage swing is a single–ended measurement operating in differential mode.

 11. Output Voltage Amplitude (V_{OHCLK} − V_{OLCLK}) at input CLOCK frequency, f_{in}. The output frequency, f_{out}, is the input CLOCK frequency divided by n, f_{out} = f_{in} ÷ n. Input CLOCK frequency is ≤3.0 GHz.

Application Information

The NB6L239 is a high-speed, low skew clock divider with two divider circuits, each having selectable clock divide ratios; $\div 1/2/4/8$ and $\div 2/4/8/16$. Both divider circuits drive a pair of differential LVPECL outputs. The internal dividers are synchronous to each other. Therefore, the common output edges are precisely aligned.

The NB6L239 clock inputs can be driven by a variety of differential signal level technologies including LVDS, LVPECL, HCSL, HSTL, or CML. The differential clock input buffer employs a pair of internal 50 Ω termination resistors in a 100 Ω center–tapped configuration and accessible via the VT pin. This feature provides transmission line termination on–chip, at the receiver end, eliminating external components. The V_{BBAC} reference output can be used to rebias capacitor–coupled

differential or single–ended input CLOCK signals. For the capacitor–coupled CLK and/or \overline{CLK} inputs, V_{BBAC} should be connected to the V_T pin and bypassed to ground with a 0.01 μF capacitor. Inputs CLK and \overline{CLK} must be signal driven or auto oscillation may result.

The common enable (EN) is synchronous so that the internal divider flip-flops will only be enabled/disabled when the internal clock is in the LOW state. This avoids any chance of generating a runt pulse on the internal clock when the device is enabled/disabled, as can happen with an asynchronous control. The internal enable flip-flop is clocked on the falling edge of the input clock. Therefore, all associated specification limits are referenced to the negative edge of the clock input.

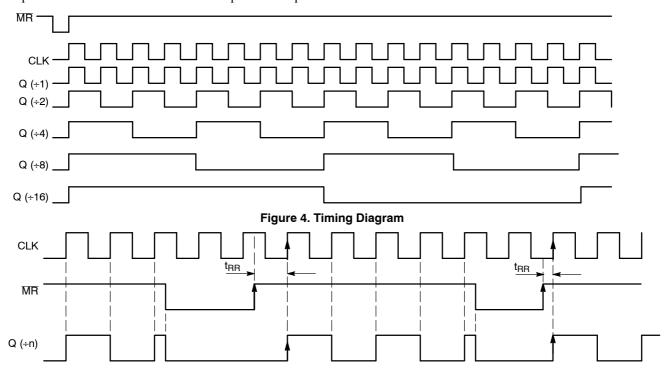


Figure 5. Master Reset Timing Diagram

NOTE: On the rising edge of \overline{MR} , Q goes HIGH after the first rising edge of CLK.

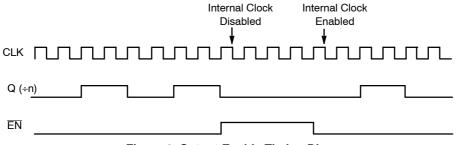
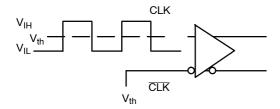


Figure 6. Output Enable Timing Diagrams

The \overline{EN} signal will "freeze" the internal divider flip-flops on the first falling edge of CLK after its assertion. The internal divider flip-flops will maintain their state during the freeze. When \overline{EN} is deasserted (LOW), and after the next falling edge of CLK, then the internal divider flip-flops will "unfreeze" and continue to their next state count with proper phase relationships.



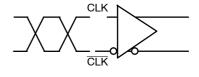


Figure 7. Differential Input Driven Single-Ended

Figure 8. Differential Inputs Driven Differentially

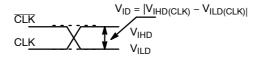
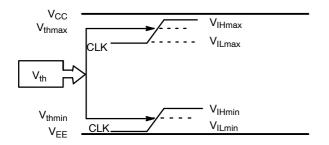
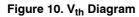


Figure 9. Differential Inputs Driven Differentially





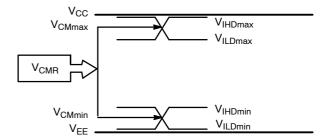


Figure 11. V_{CMR} Diagram

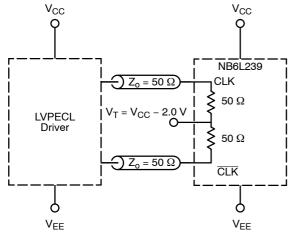


Figure 12. LVPECL Interface

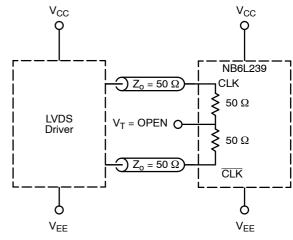


Figure 13. LVDS Interface

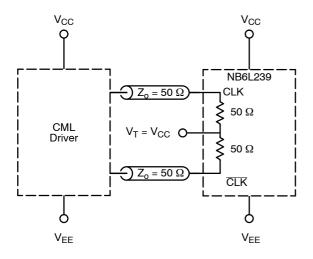


Figure 14. Standard 50 Ω Load CML Interface

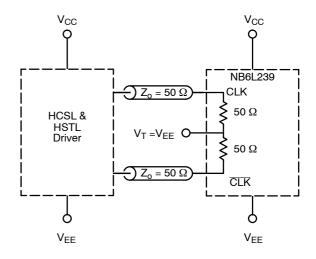


Figure 15. Standard 50 Ω Load HCSL & HSTL Interface

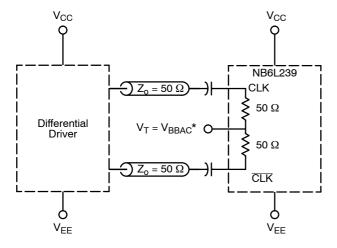
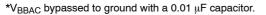


Figure 16. Capacitor–Coupled Differential Interface (V_T Connected to V_{BBAC})



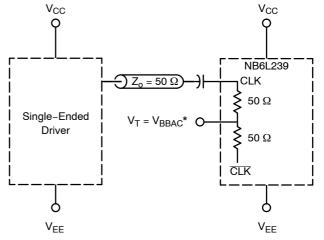


Figure 17. Capacitor–Coupled Single–Ended Interface (V_T Connected to V_{BBAC})

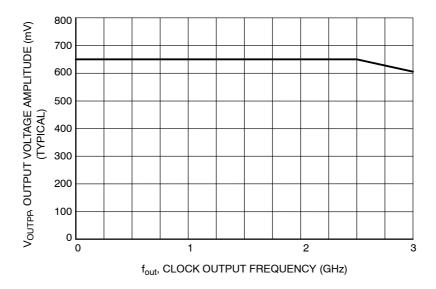


Figure 18. Output Voltage Amplitude (V_{OUTPP}) versus Clock Output Frequency at Ambient Temperature (Typical) (f_{out} QA/QB) = $f_{in} \div n$; $f_{in} \le 3.0$ GHz).

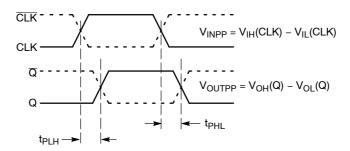


Figure 19. AC Reference Measurement

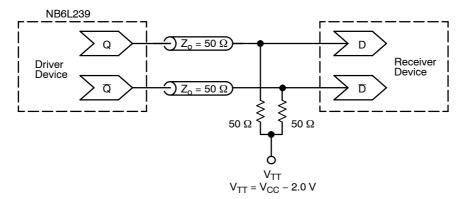


Figure 20. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
NB6L239MNG	QFN-16, 3 x 3 mm (Pb-Free)	123 Units / Rail
NB6L239MNR2G	QFN-16, 3 x 3 mm (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

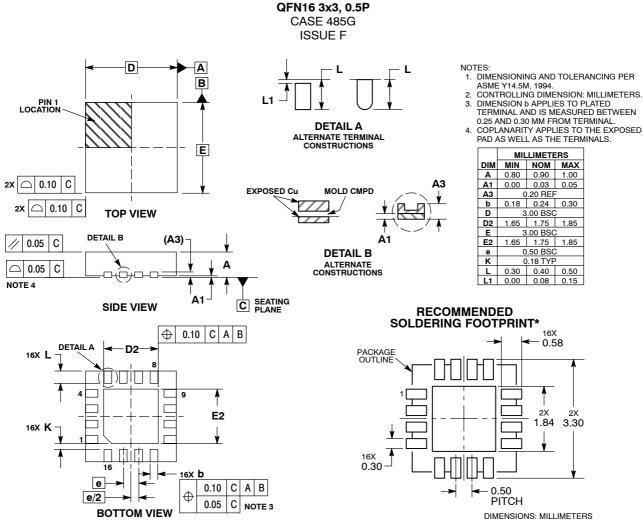
AND8002/D - Marking and Date Codes

AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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